

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the application:

1. (currently amended) An end use device having a known good die (KGD), the KGD having solder ball array and wire bond connections;

the KGD having solder ball array connections on a planar KGD surface;

the KGD having an array of wire bond connections on the planar KGD ~~planar~~ surface;

the KGD having electrical connections between all of the solder ball array connections and the wire bond connections;

wherein the KGD is a KGD which is thermal stress tolerance tested prior to mounting the KGD on the end use device by a test device connected to the KGD by the wire bond connections or in the alternative by the solder ball connections;

wherein when either the wire bond connections are used or the solder ball connections are used for a known good die test, the other connections are connected to the end use device; and the connections used for the known good die test are not connected to the end use device or any other device, when the KGD is connected to the end use device.

2. (previously presented) The end use device in accordance with claim 1, wherein when either the wire bond connections or solder

ball connections is used for the known good die test, the other is not affected by the known good die (KGD) test and remains pristine until connected to the end use device.

3 and 4. (canceled)

5. (previously presented) The end use device in accordance with claim 1, wherein the solder ball array connections or wire bond connections which are used when the die is tested are not removed from the die.

6. (previously presented) The end use device in accordance with claim 1, wherein connections to the test device are metallurgical connections.

7. (previously presented) The end use device in accordance with claim 1, wherein the solder ball array connections are controlled collapse chip connections.

8 - 10. (canceled)

44. (canceled)